

FOR IMMEDIATE RELEASE

GOWIN SEMICONDUCTOR TO SHOWCASE NEW EMBEDDED ARM CORE FPGA PRODUCTS AT ARM TECHCON 2018

Guangzhou, China and San Jose, CA, September 2018 – GOWIN Semiconductor Corp., the world’s leading innovator of programmable logic devices, will be exhibiting its new family of embedded Arm core FPGAs at Arm TechCon 2018 in San Jose, California.

GOWIN staff will be available to meet during the conference in booth #1226 to discuss the new products. In addition, demonstrations will be ongoing to show the feature set of the new product family suitable for various applications.

“These new products address the needs required in distributed computing, especially at the edge, where resources are limited. Power and size are a concern for edge implementations. GOWIN’s innovative approach addresses these concerns with optimized solutions,” said Scott Casper, Director of Sales, Americas, for GOWIN Semiconductor. “We are excited to participate in Arm TechCon 2018 to showcase our new embedded Arm core FPGA solutions. These solutions will allow designers to face the challenges with edge applications.”

GOWIN’s new embedded Arm core FPGA products include an Arm Cortex-M3 with an FPGA fabric, Flash NVM, SRAM, ADC, USB, and MIPI PHY. In addition, this device comes with an optional 32Mb of embedded memory, allowing for a true SoC solution. GOWIN will be exhibiting at ArmTechCon 2018 in booth #1226 from October 16-18. To request a meeting, please call (408) 646-2118 or send a request to scott@gowinsemi.com.